

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	external electrode and thermosetting conductive paste and resin	US-PGPUB; USPAT	ADJ	ON	2007/11/14 13:59
S2	184	conductive particle and melting point and metal powder and resin and conductive and thermosetting	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:00
S3	137	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:01
S4	38	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:04
S5	15	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:06
S6	15	conductive particle and melting point and metal powder and resin and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:07
S7	749	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6	US-PGPUB; USPAT	ADJ	ON	2007/11/15 13:04

S8	583	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2007/11/15 13:08
S9	198	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature)	US-PGPUB; USPAT	ADJ	ON	2007/11/15 13:08
S10	136	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature) and electrode	US-PGPUB; USPAT	ADJ	ON	2007/11/15 14:03
S11	624	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/11/15 14:04
S12	137	S11 and conductive (paste or adhesive)	US-PGPUB; USPAT	ADJ	ON	2007/11/15 14:47
S13	0	H10-172346	JPO; DERWENT	ADJ	ON	2007/11/15 14:49
S14	14	"172346"	JPO; DERWENT	ADJ	ON	2007/11/15 14:49
S15	0	terminal electrode for electronic component	JPO; DERWENT	ADJ	ON	2007/11/15 14:50
S16	624	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/11/16 08:56
S17	137	S16 and conductive (paste or adhesive) and (tin or sn or indium or in)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 08:56
S18	60	S16 and conductive (paste or adhesive) and (tin or sn or indium)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 08:56

S19	15	("4016463" "4759965" "5375035" "5568352" "5793600" "6002575" "6060150" "6292352" "6300686").PN. OR ("6525921").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/16 09:15
S20	198	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 09:19
S21	29	conductive (paste or adhesive).ti. and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 09:22
S22	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124"	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/16 09:47

"4352899"
"4353816"
"4368281"
"4396666"
"4400214"
"4415486"
"4429657"
"4434084"
"4457861"
"4459166"
"4496475"
"4533685"
"4557857"
"4564563"
"4575432"
"4578425"
"4581158"
"4592861"
"4639396"
"4652398"
"4673532"
"4678602"
"4680141"
"4683653"
"4696764"
"4705647"
"4731130"
"4732702"
"4733018"
"4740252"
"4756756"
"4765929"
"4775500"
"4780371"
"4786437"
"4789411"
"4803543"
"4808434"
"4816184"
"4820446"
"4830779"
"4836955"
"4859268"
"4872928"
"4874548"
"4880570"
"4882227"
"4888135"
"4894184"
"4940498"
"4971727"
"4996005"
"5088189"
"5136365"
"5376403"

		"5463190").PN. OR ("5853622").URPN.				
S23	90	S22 and (weight or mass)	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/16 09:53
S24	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124" "4352899" "4353816" "4368281" "4396666" "4400214" "4415486" "4429657" "4434084" "4457861" "4459166" "4496475" "4533685" "4557857" "4564563" "4575432" "4578425" "4581158" "4592861" "4639396" "4652398" "4673532" "4678602" "4680141" "4683653" "4696764"	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/19 06:38

		"4705647" "4731130" "4732702" "4733018" "4740252" "4756756" "4765929" "4775500" "4780371" "4786437" "4789411" "4803543" "4808434" "4816184" "4820446" "4830779" "4836955" "4859268" "4872928" "4874548" "4880570" "4882227" "4888135" "4894184" "4940498" "4971727" "4996005" "5088189" "5136365" "5376403" "5463190").PN. OR ("5853622").URPN.				
S27	3007	layer and capacitor and external electrode	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/03 16:41
S28	313	S27 and thermosetting	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/03 16:42
S29	60	S28 and conductive particles	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/03 16:42
S30	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/03 16:48
S31	4	external electrode and thermosetting conductive paste and resin	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18

S32	186	conductive particle and melting point and metal powder and resin and conductive and thermosetting	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S33	138	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S34	38	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S35	15	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S36	15	conductive particle and melting point and metal powder and resin and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S37	773	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S38	601	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18

S39	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S40	139	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature) and electrode	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S41	647	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S42	147	S41 and conductive (paste or adhesive)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S43	0	H10-172346	JPO; DERWENT	ADJ	ON	2008/03/04 06:18
S44	27	"172346"	JPO; DERWENT	ADJ	ON	2008/03/04 06:18
S45	0	terminal electrode for electronic component	JPO; DERWENT	ADJ	ON	2008/03/04 06:18
S46	647	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S47	147	S46 and conductive (paste or adhesive) and (tin or sn or indium or in)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S48	64	S46 and conductive (paste or adhesive) and (tin or sn or indium)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S49	15	("4016463" "4759965" "5375035" "5568352" "5793600" "6002575" "6060150" "6292352" "6300686").PN. OR ("6525921").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18

S50	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S51	29	conductive (paste or adhesive).ti. and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S52	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124" "4352899" "4353816" "4368281" "4396666" "4400214" "4415486" "4429657" "4434084" "4457861" "4459166" "4496475"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18

		"4533685" "4557857" "4564563" "4575432" "4578425" "4581158" "4592861" "4639396" "4652398" "4673532" "4678602" "4680141" "4683653" "4696764" "4705647" "4731130" "4732702" "4733018" "4740252" "4756756" "4765929" "4775500" "4780371" "4786437" "4789411" "4803543" "4808434" "4816184" "4820446" "4830779" "4836955" "4859268" "4872928" "4874548" "4880570" "4882227" "4888135" "4894184" "4940498" "4971727" "4996005" "5088189" "5136365" "5376403" "5463190").PN. OR ("5853622").URPN.				
S53	90	S52 and (weight or mass)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18

S54	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124" "4352899" "4353816" "4368281" "4396666" "4400214" "4415486" "4429657" "4434084" "4457861" "4459166" "4496475" "4533685" "4557857" "4564563" "4575432" "4578425" "4581158" "4592861" "4639396" "4652398" "4673532" "4678602" "4680141" "4683653" "4696764" "4705647" "4731130" "4732702" "4733018"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
-----	-----	---	---------------------------	-----	----	---------------------

		"4740252" "4756756" "4765929" "4775500" "4780371" "4786437" "4789411" "4803543" "4808434" "4816184" "4820446" "4830779" "4836955" "4859268" "4872928" "4874548" "4880570" "4882227" "4888135" "4894184" "4940498" "4971727" "4996005" "5088189" "5136365" "5376403" "5463190").PN. OR ("5853622").URPN.				
S55	3010	layer and capacitor and external electrode	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S56	314	S55 and thermosetting	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S57	60	S56 and conductive particles	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S58	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S59	109	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:33

S60	0	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive powder and conductive particle	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:40
S61	7	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive powder	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:41
S62	19	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive particle	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:41
S63	960	conductive (paste or adhesive) and (weight or mass) with (percent or "%") and conductive particle	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:52
S64	109	conductive (paste or adhesive) and (weight or mass) with (percent or "%") and conductive particle and conductive powder	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:52
S65	22	conductive (paste or adhesive) and (weight or mass) with (percent or "%") and conductive particle and conductive powder and low with melting with (point or temperature)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:55

S66	8	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive powder	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 13:15
S67	913	electrode and (conductive near3 paste) same (tin or sn or indium) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 13:55
S68	29	electrode and (conductive near3 paste) same (tin or sn or indium) same resin and (tin or sn or indium) same("wt%" or ((weight or mass or wt) near2 (percent or "%"))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:08
S69	136	((TAKESHI) near2 (KIMURA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S70	2	((YAMATO) near2 (TAKADA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S71	3	((MICHINORI) near2 (KOMAGATA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S72	35	((MASAHIRO) near2 (KITAMURA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S73	1	((KIMINORI) near2 (YOKOYAMA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S74	130	electrode and (conductive near3 (paste or adhesive)) same (tin or sn or indium) and (tin or sn or indium) same("wt %" or ((weight or mass or wt) near2 (percent or "%"))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:20
S75	180	((MASAHIRO) near2 (KITAMURA)).INV.	JPO; DERWENT	ADJ	ON	2008/07/08 14:20
S76	11	((MICHINORI) near2 (KOMAGATA)).INV.	JPO; DERWENT	ADJ	ON	2008/07/08 14:21

S77	12	("3947956" "4795670" "5744758" "5879788" "5977490" "6207259" "6440542" "6459046").PN. OR ("6641898").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/07/08 14:30
S78	55	(conductive near3 (paste or adhesive)). ab. and (tin or sn or indium) same("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:34
S79	105	(conductive near3 (paste or adhesive)). ab. and (tin or sn or indium) same("wt%" or ((weight or mass or wt) near2 (percent or "%"))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:45
S80	1	1979-24588B.NRAN.	DERWENT	ADJ	ON	2008/07/09 08:24
S81	1	"54022596"	JPO	ADJ	ON	2008/07/09 08:25
S82	1	("5128827").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/02/09 13:20
S83	11	"10279903" OR "10022170"	JPO; DERWENT	ADJ	ON	2009/02/10 12:55
S85	104	(conductive near3 (paste or adhesive)). ab. and (tin or sn or indium) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/05/31 19:25
S86	36	(conductive near3 (paste or adhesive)). ab. and (tin or sn or indium) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/05/31 19:25

S87	352	(conductive near3 (paste or adhesive)) and (tin or sn or indium) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 06:59
S88	306	(conductive near3 (paste or adhesive)) and (tin or sn or indium) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5 and (powder or particle)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:01
S89	162	(conductive near3 (paste or adhesive)) and (tin or sn or indium) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5 and (powder or particle) with (tin or sn or indium)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:05
S90	766	(conductive near3 (paste or adhesive)) and ((Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or sn or indium or bi or bismuth)) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5 and (powder or particle) with (Francium or Fr	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:15

		or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth)				
S91	119	(conductive near3 (paste or adhesive)). ab,ti. and ((Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth)) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5 and (powder or particle) with (Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:15
S92	10	("4221925" "4303715" "5227588" "5473120" "5744758" "5977490" "6087597" "6329610").PN. OR ("6713687").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/06/01 07:31

S93	132	(conductive near3 (paste or adhesive)) with (electrode or electronic or electrical) and ((Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth)) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and thermoset\$5 and (powder or particle) with (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:35
S94	121	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) with capacitor.ab,ti. and (terminal or external) same (thermoset\$4 or epoxy) and conductive near2 (adhesive or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:01
S95	921	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same (thermoset\$4 or epoxy) and conductive near2 (adhesive or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:14
S96	290	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same (thermoset\$4 or epoxy) same conductive near2 (adhesive or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:17

S98	451	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:24
S101	268	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (cured or cure or curing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:30
S102	390	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:34
S103	98	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (powder or particle) with (Francium or Fr or	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 10:17

		Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth)				
S104	55	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab,ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (powder or particle) with (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or li or lithium or tin or sn or indium or bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 10:19
S110	457	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth) same (gold or silver or copper or ag or au or cu) same (thermoset \$4 or epoxy) and first near3 (metal or conductive or powder or particle) and second near3 (metal or conductive or powder or particle)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/06/01 10:54

S111	242	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth) same (gold or silver or copper or Ag or Au or Cu) same (thermoset \$4 or epoxy) and first near3 (metal or conductive or powder or particle) and second near3 (metal or conductive or powder or particle) and (electrode or electronic or electrical) and (paste or adhesive) near3 conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 10:54
S112	731	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth) same (gold or silver or copper or Ag or Au or Cu) same (thermoset \$4 or epoxy) and (electrode or electronic or electrical) and (paste or adhesive) near3 conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:17
S114	242	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or Li or lithium or tin or Sn or indium or Bi or bismuth) same (gold or silver or copper or Ag or Au or Cu) same (thermoset \$4 or epoxy) and first near3 (metal or conductive or powder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:19

		or particle) and second near3 (metal or conductive or powder or particle) and (electrode or electronic or electrical) and (paste or adhesive) near3 conductive				
S115	489	S112 not S114	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:19
S116	135	S115 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:19
S117	2	((("5,538,789") or ("5,565,267,"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/06/01 13:34
S118	354	S115 not S116	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 14:11

6/ 2/ 2009 8:44:06 AM

C:\ Documents and Settings\ dsinclair\ My Documents\ EAST\ Workspaces\ 10\ 53\ 10538136.
wsp